



SOT1938-2

HQFN23, thermal enhanced quad flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body

22 October 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN23
Package type industry code	HQFN23
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	16-07-2018
Manufacturer package code	98ASA00495D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	12	-	mm
package width	-	12	-	mm
seated height	-	2.1	-	mm
nominal pitch	-	0.9	-	mm
actual quantity of termination	-	23	-	



HQFN23, thermal enhanced qual flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body

2 Package outline

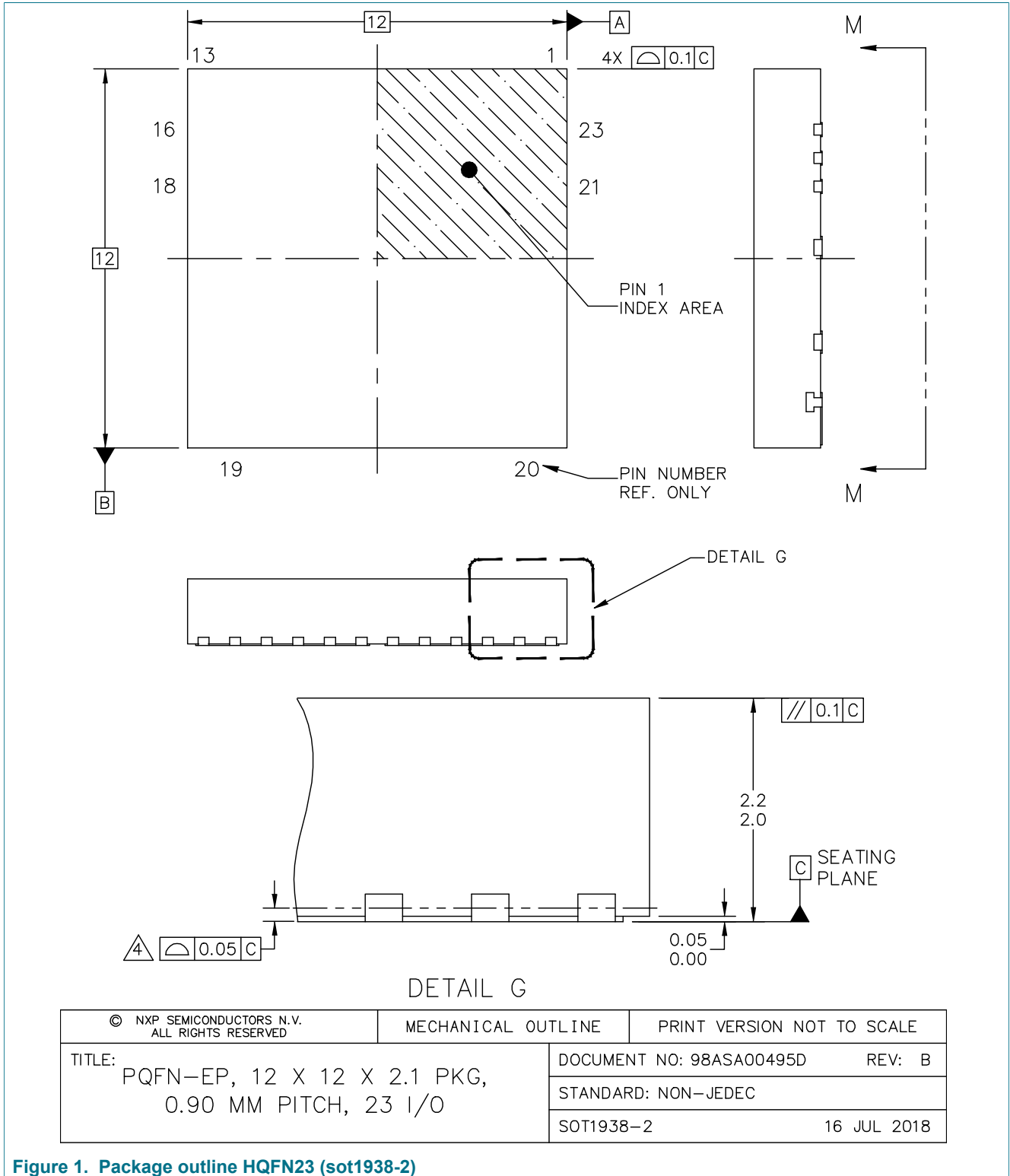
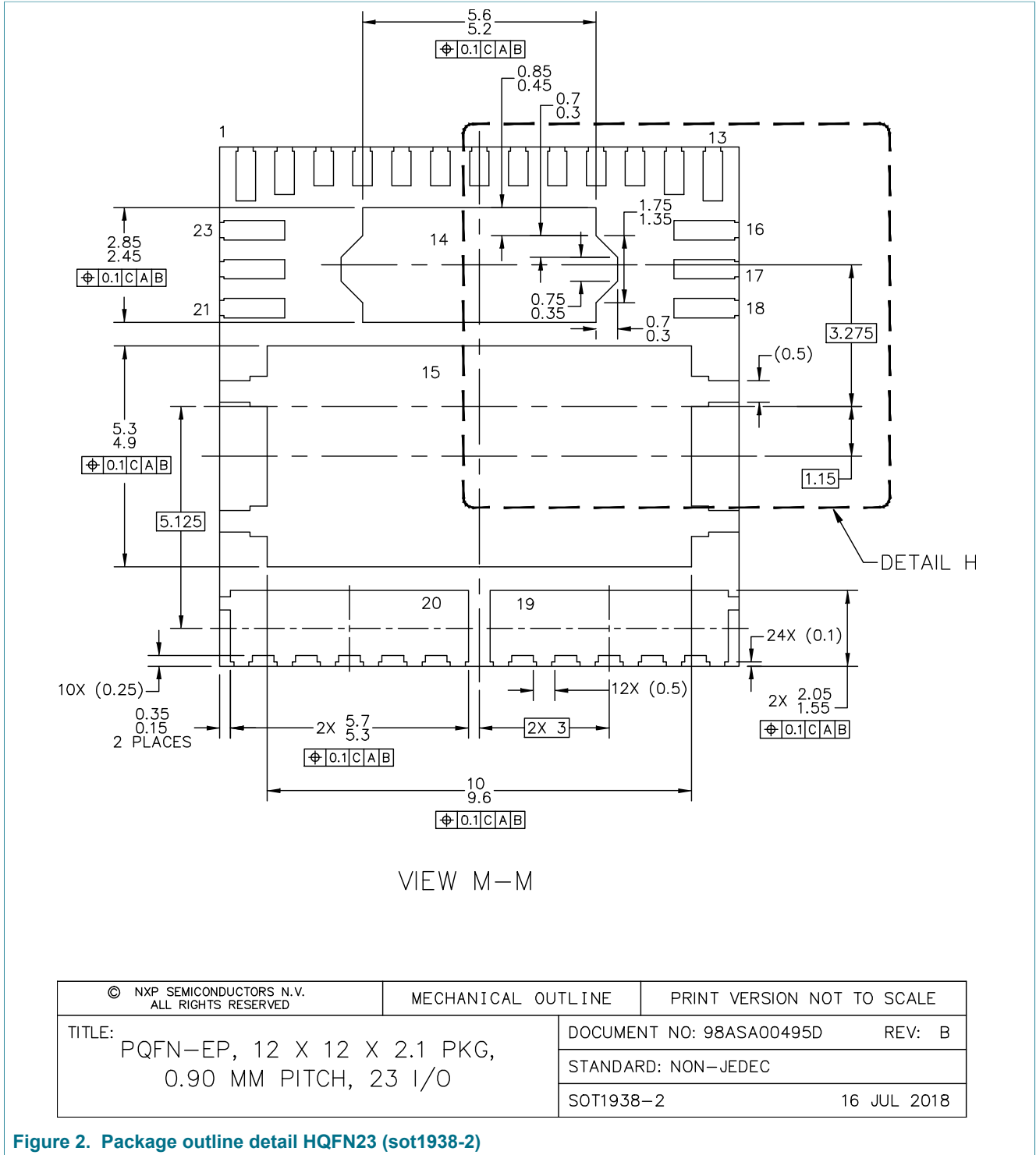


Figure 1. Package outline HQFN23 (sot1938-2)

HQFN23, thermal enhanced qual flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body



HQFN23, thermal enhanced qual flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body

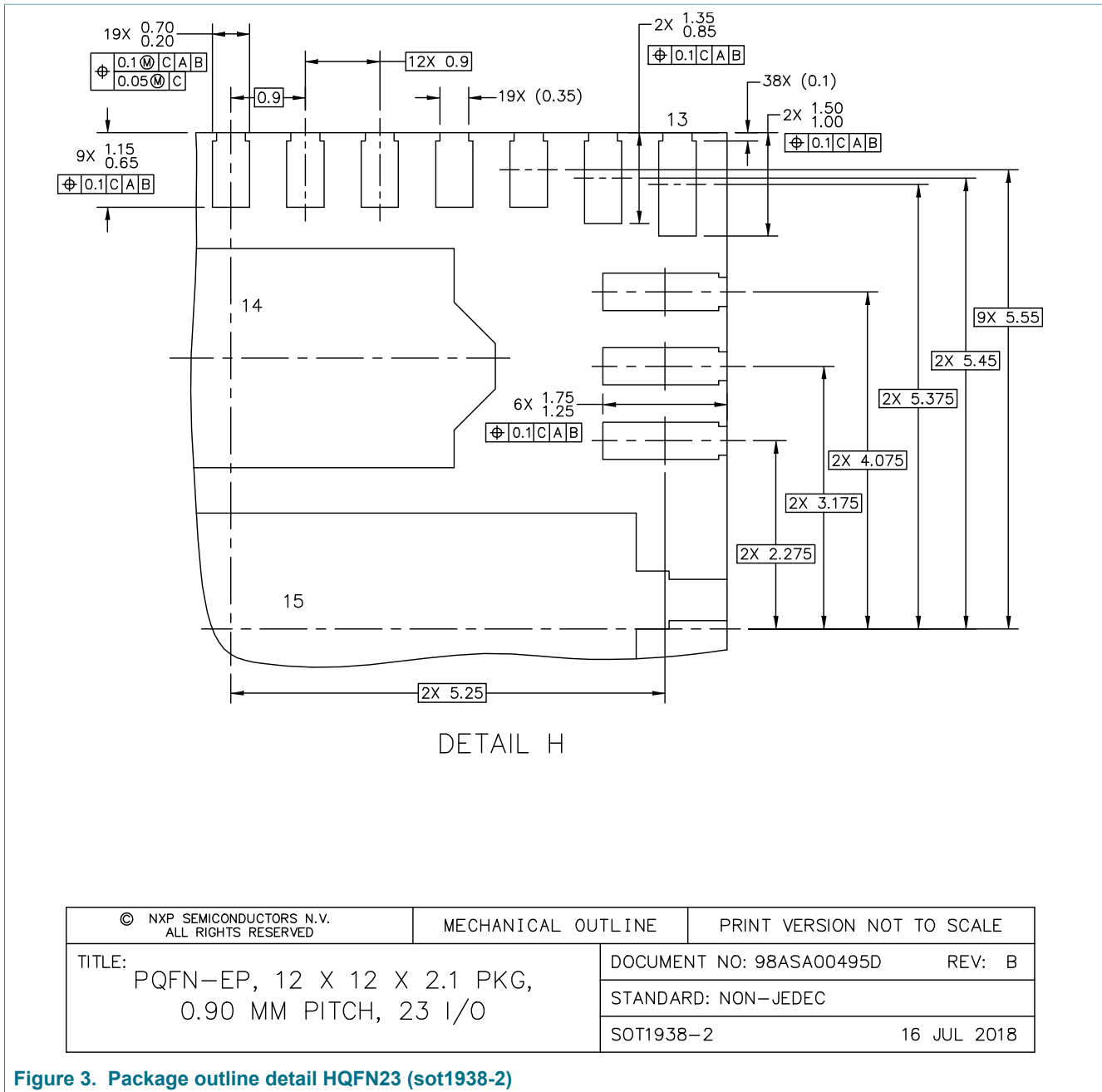



Figure 3. Package outline detail HQFN23 (sot1938-2)

HQFN23, thermal enhanced qual flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFP-N.
4.  COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP IS GUARANTEED TO BE 0.25MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: PQFN-EP, 12 X 12 X 2.1 PKG, 0.90 MM PITCH, 23 I/O		DOCUMENT NO: 98ASA00495D	REV: B
		STANDARD: NON-JEDEC	
		SOT1938-2	16 JUL 2018

Figure 4. Package outline note HQFN23 (sot1938-2)

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

HQFN23, thermal enhanced qual flat package, no leads, 23 terminals, 0.9 mm pitch, 12 mm x 12 mm x 2.1 mm body

Contents

1 Package summary1
2 Package outline2
3 Legal information6